

Title (en)

Resist compositions for circuit boards

Title (de)

Resistzusammensetzungen für Leiterplatten

Title (fr)

Compositions formant réserve pour plaquettes à circuits

Publication

EP 0802456 A1 19971022 (EN)

Application

EP 97110145 A 19940506

Priority

- EP 94107156 A 19940506
- JP 10640693 A 19930507

Abstract (en)

A resist composition having an excellent heat resistance and capable of sufficiently withstanding to an alkali bath at pH of not less than 14 and a bath temperature of 80 DEG C is provided without degrading photosensitive properties by using an uncured novolac type epoxy resin, a part of epoxy group of which is acrylated, as a resin component of a photosensitive resin matrix and adding an imidazole curing agent. <IMAGE>

IPC 1-7

G03F 7/038

IPC 8 full level

C08F 290/00 (2006.01); **C08F 299/02** (2006.01); **C08G 59/17** (2006.01); **C08G 59/20** (2006.01); **G03F 7/004** (2006.01); **G03F 7/027** (2006.01); **G03F 7/032** (2006.01); **G03F 7/038** (2006.01); **H05K 1/03** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP)

G03F 7/032 (2013.01); **G03F 7/038** (2013.01); **H05K 3/184** (2013.01)

Citation (search report)

- [X] DE 3925895 A1 19900215 - FUJI PHOTO FILM CO LTD [JP]
- [X] FR 2580828 A1 19861024 - TAIYO INK MFG CO LTD [JP]
- [A] DE 3717199 A1 19871126 - HITACHI LTD [JP]
- [A] US 5175060 A 19921229 - ENOMOTO RYO [JP], et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 014, no. 001 (P - 985) 8 January 1990 (1990-01-08)

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